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Bulletin Date: 12/11/2014		Bulletin Effective Date: 12/11/2014	
Title: EFM32GG900 Datasheet Revision Notification			
Originator: Ted Batey		Phone: 512-532-5279	Dept: Marketing
Customer Contact: Kathy Haggar		Phone: 512-532-5261	Dept: Sales
Bulletin Details			
Description: Silicon Labs is pleased to announce version 1.1 of the EFM32GG900 Giant Gecko wafer sale datasheet is now available. This revision updates section 3.4 Bonding Instructions with a recommendation to use gold bond wires. An Environmental section (3.5.1) has also been added which discusses potential bare die sensitivity to ambient light.			
Reason: This bulletin recommends that customers purchasing wafers and designing their own packages use gold bond wires. Customers using bare die also need to be aware of potential light sensitivity.			
Product Identification: EFM32GG900F512G-D-D1I EFM32GG900F1024G-D-D1I			
This change is considered a minor change which does not affect form, fit, function, quality, or reliability. The information is being provided as a customer courtesy. Please contact your local Silicon Labs sales representative with any questions about this notification. A list of Silicon Labs sales representatives may be found at www.silabs.com			
Customer Actions Needed: Review packaging and bonding design to ensure use of gold bond wires.			